EE 330 Lecture 39

Digital Circuits

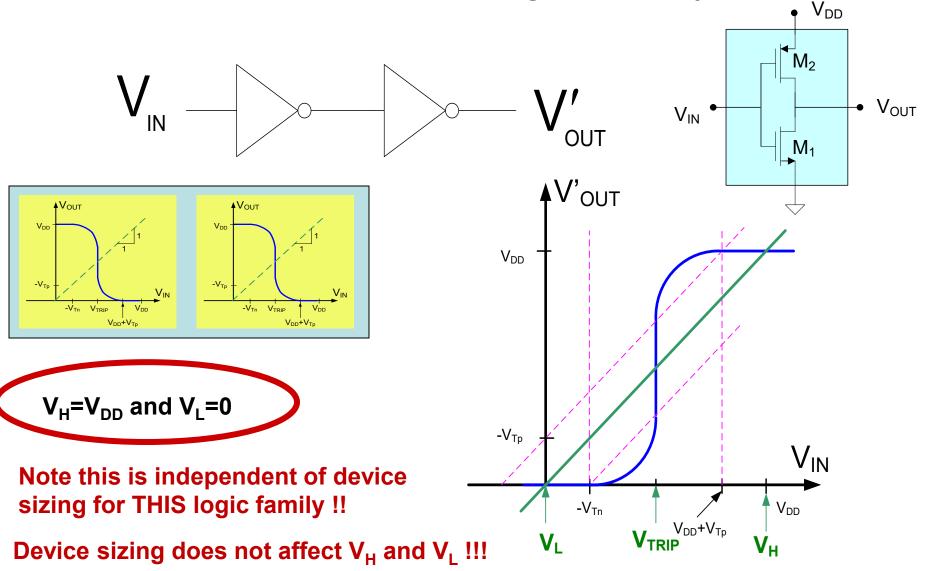
Sizing of Devices for Logic Circuits Ratio Logic Other MOS Logic Families Propagation Delay – basic characterization

Spring 2024 Exam Schedule

- Exam 1 Friday Feb 16
- Exam 2 Friday March 8
- Exam 3 Friday April 19

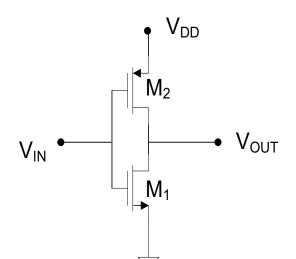
Final Exam Tuesday May 7 7:30 AM - 9:30 AM

Inverter Transfer Characteristics of Inverter Pair for <u>THIS</u> Logic Family



Review from last lecture Transfer characteristics of the static CMOS inverter (Neglect λ effects) V_{OUT} V_{DD} $-V_{Tp}$ V_{IN} From Case 3 analysis: V_{DD} V_{Tn} V_{TRIP} $= \frac{\left(V_{Tn}\right) + \left(V_{DD} + V_{Tp}\right) \sqrt{\frac{\mu_{p}}{\mu_{n}}} \frac{W_{2}}{W_{1}} \frac{L_{1}}{L_{2}}}{1 + \sqrt{\frac{\mu_{p}}{\mu_{n}}} \frac{W_{2}}{W} \frac{L_{1}}{L_{1}}}$ V_{DD}+V_{Tp} $V_{IN} =$

Sizing of the Basic CMOS Inverter

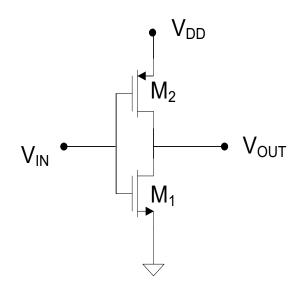


Most logic families require using the device sizing variables to determine acceptable V_H and V_L values

The characteristic that device sizes do not need to be used to establish V_H and V_L logic levels is a major advantage of this type of logic !!

How should M_1 and M_2 be sized?

How many degrees of freedom are there in the design of the inverter?



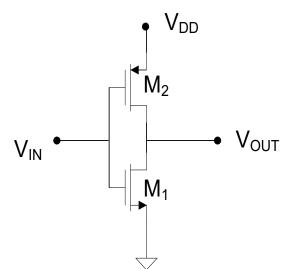
How many degrees of freedom are there in the design of the inverter?

$$\{W_1, W_2, L_1, L_2\}$$
 4 degrees of freedom

But in basic device model and in <u>most</u> performance metrics, W_1/L_1 and W_2/L_2 appear as ratios

 $\{ W_1/L_1, W_2/L_2 \}$

effectively 2 degrees of freedom



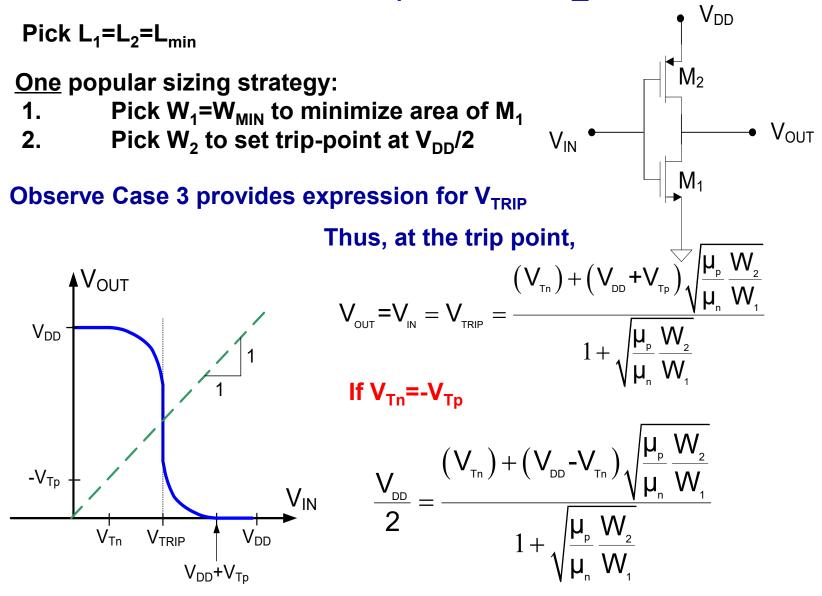


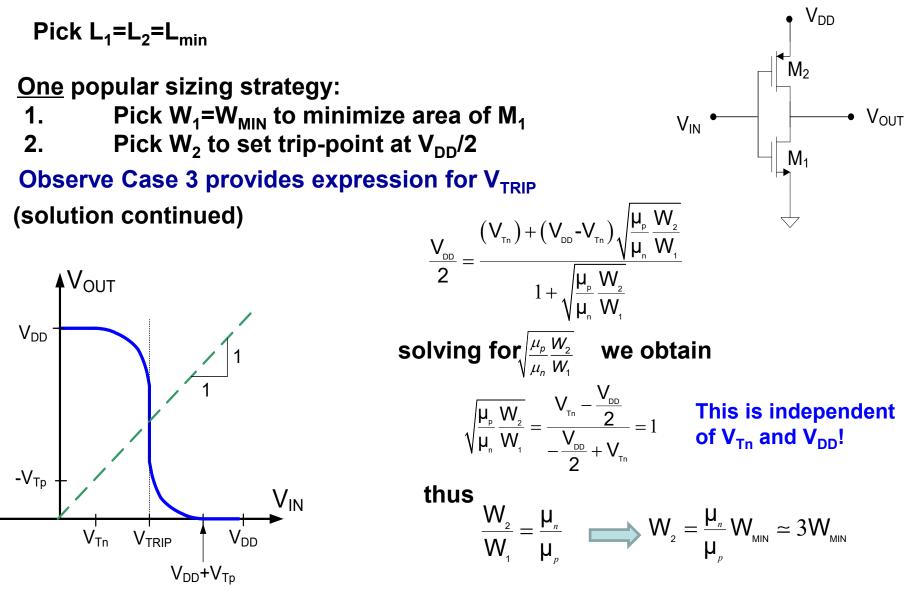
That leaves $\{W_1, W_2\}$

effectively 2 degrees of freedom

How are W_1 and W_2 chosen?

Depends upon what performance parameters are most important for a given application!



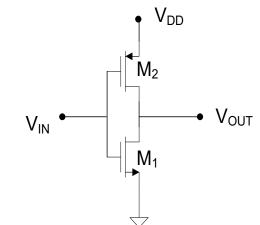


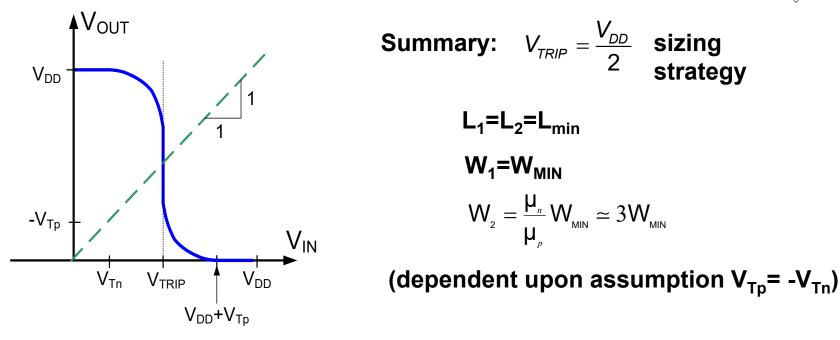
Pick L₁=L₂=L_{min}

One popular sizing strategy:

- 1. Pick $W_1 = W_{MIN}$ to minimize area of M_1
- 2. Pick W_2 to set trip-point at $V_{DD}/2$

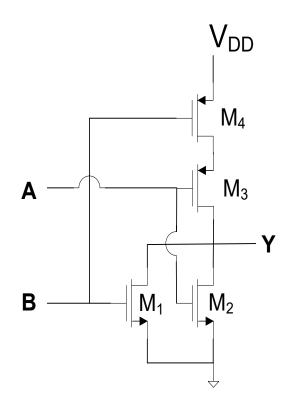
Observe Case 3 provides expression for V_{TRIP}

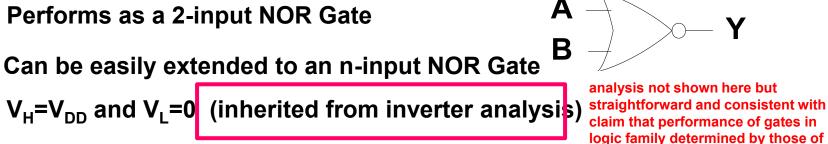


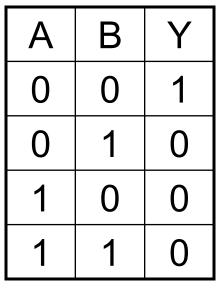


Other sizing strategies will be discussed later !

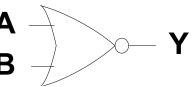
Extension of Basic CMOS Inverter to Multiple-Input Gates





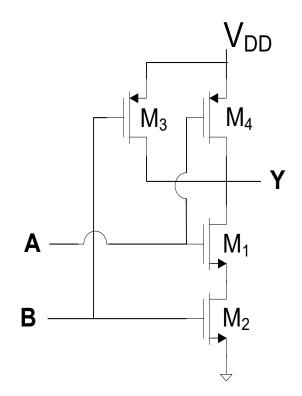


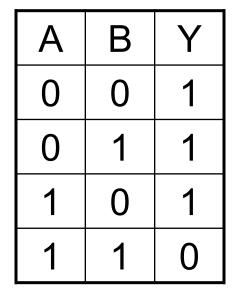
Truth Table



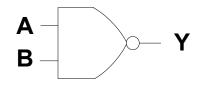
basic inverter

Extension of Basic CMOS Inverter to Multiple-Input Gates





Truth Table

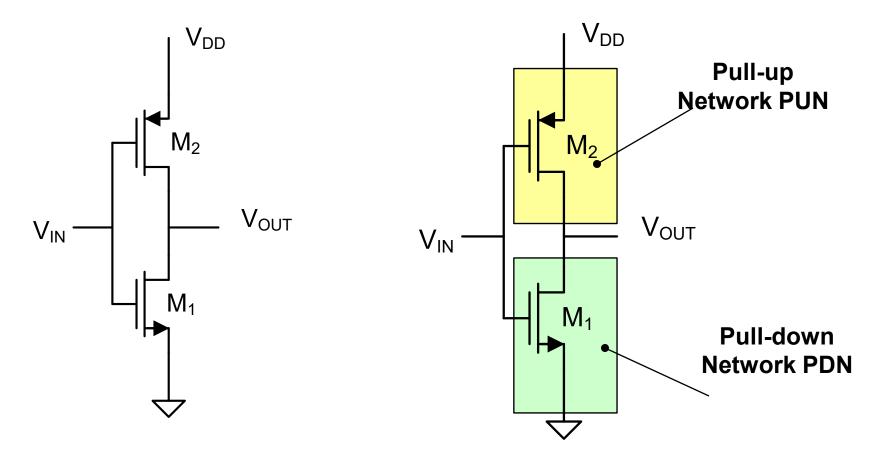


Performs as a 2-input NAND Gate

Can be easily extended to an n-input NAND Gate

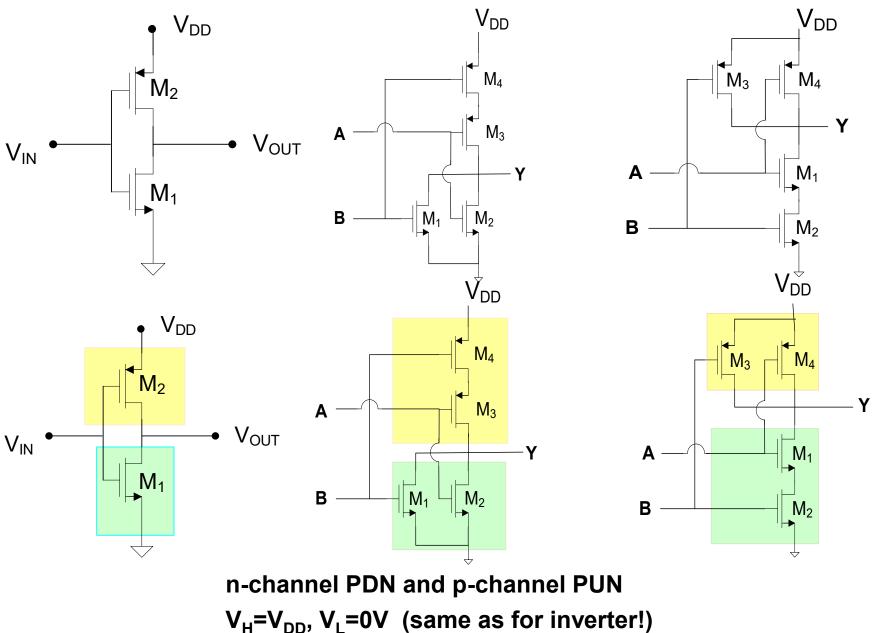
 $V_{H}=V_{DD}$ and $V_{L}=0$ (inherited from inverter analysis)

Static CMOS Logic Family



Observe PUN is p-channel, PDN is n-channel V_H=V_{DD} and V_L=0 (inherited from inverter analysis)

Static CMOS Logic Family

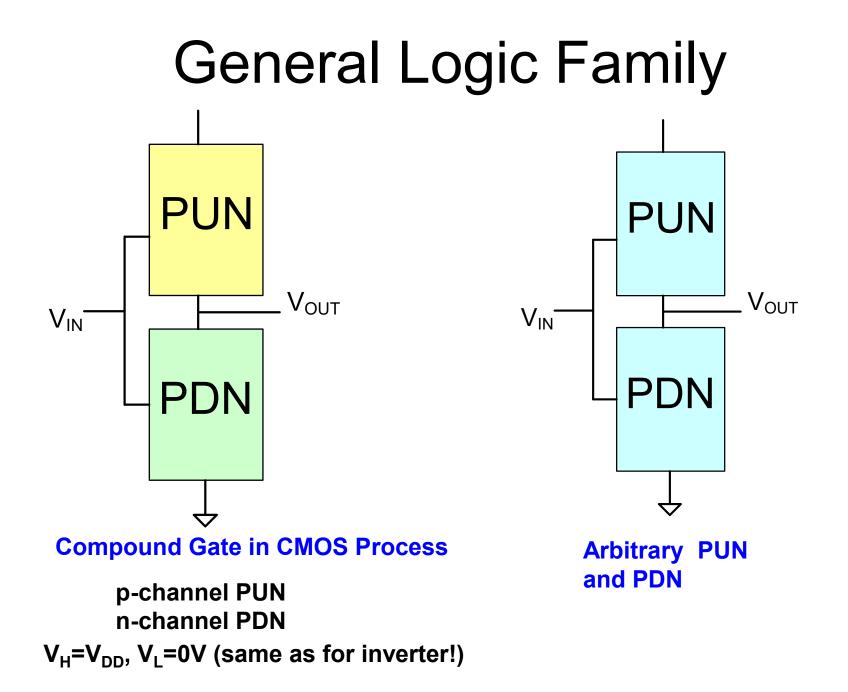


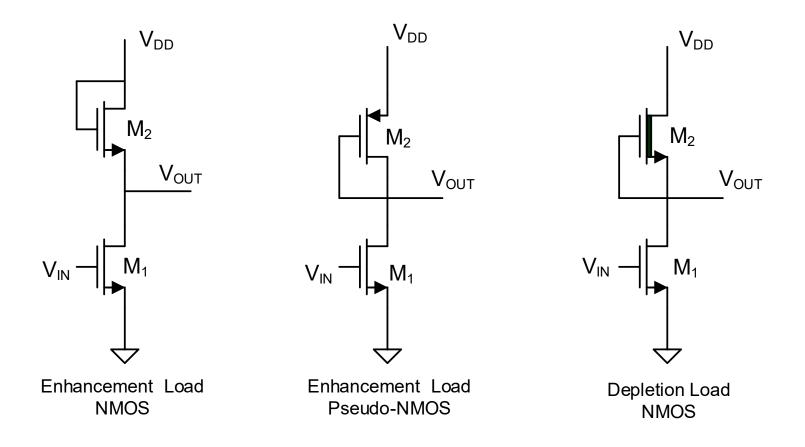
Digital Circuit Design

- Hierarchical Design
- Basic Logic Gates
 - Properties of Logic Families
 - Characterization of CMOS Inverter
- Static CMOS Logic Gates
 - Ratio Logic
 - Propagation Delay
 - Simple analytical models
 - FI/OD
 - Logical Effort
 - Elmore Delay
 - Sizing of Gates
 - The Reference Inverter

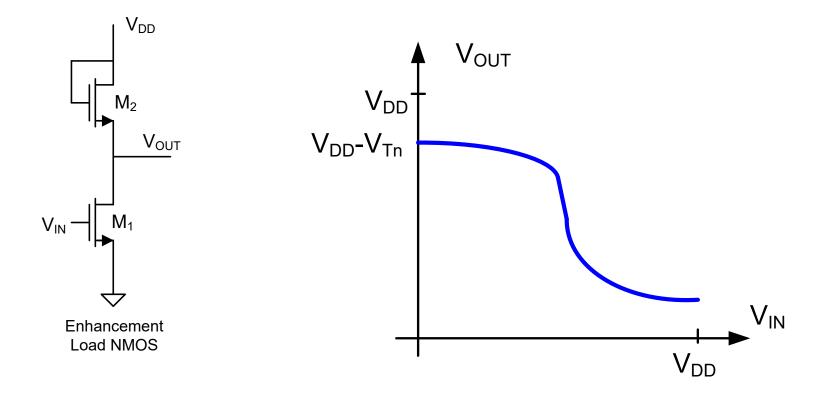
- Propagation Delay with Multiple Levels of Logic
- Optimal driving of Large Capacitive Loads
- Power Dissipation in Logic Circuits
- Other Logic Styles
- Array Logic
- Ring Oscillators



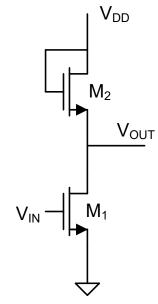




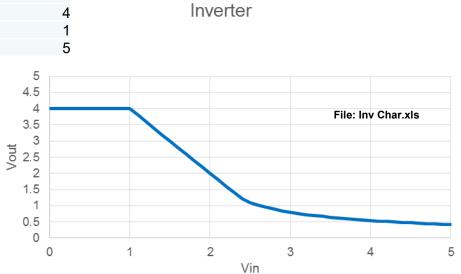
These are termed "ratio logic" gates



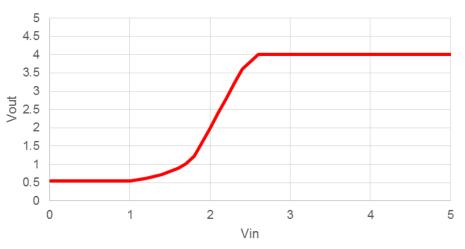
NMOS example



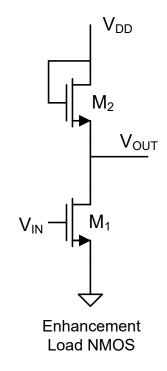
Enhancement Load NMOS VTH 1 W1/L1 4 W2/L2 1 VDD 5



Inverter Pair



NMOS example

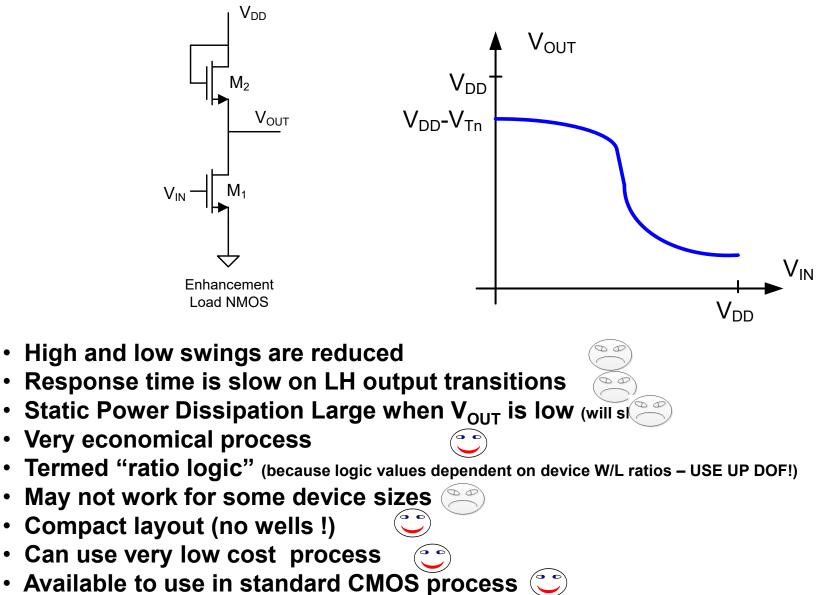


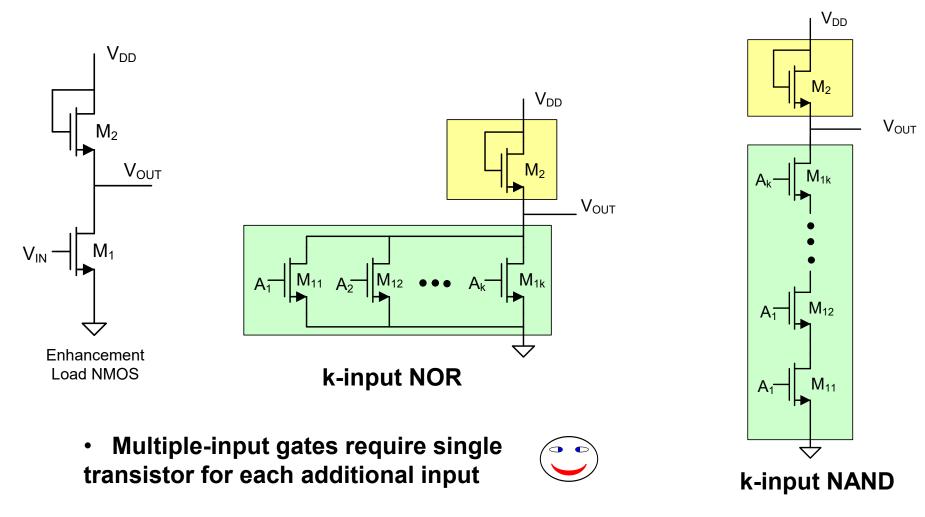
| 1 |
|---|
| 4 |
| 1 |
| 5 |
| |

Inverter Pair



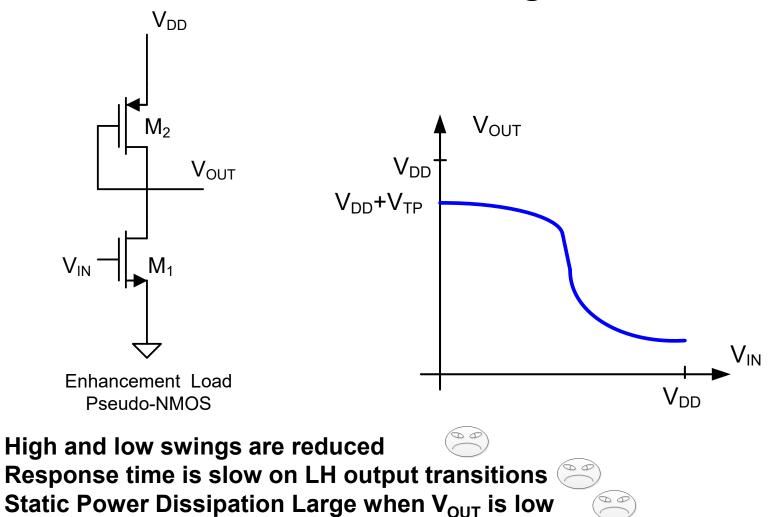
V_H=4V V_L=0.55V V_{TRIP}=2V





• Still useful if many inputs are required (will be shown that static power does not increase with k)



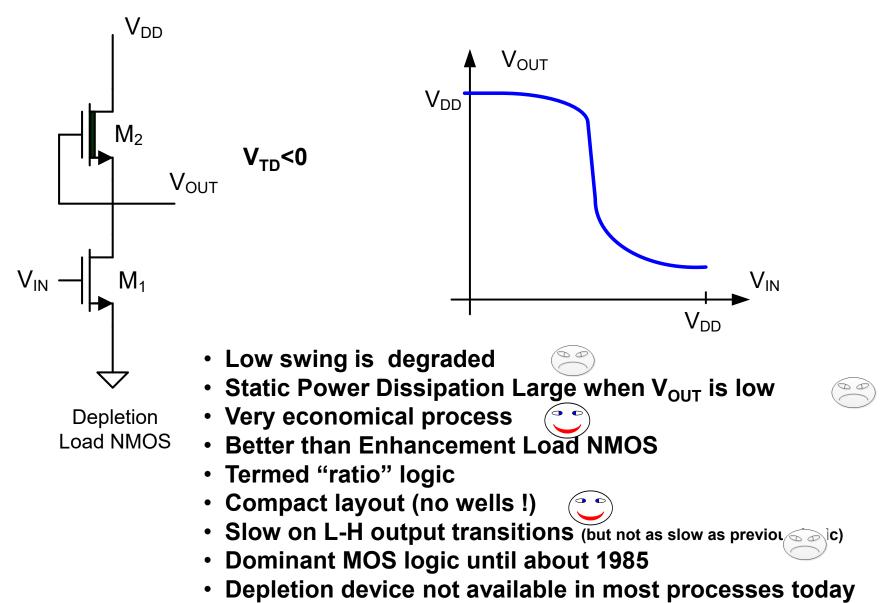


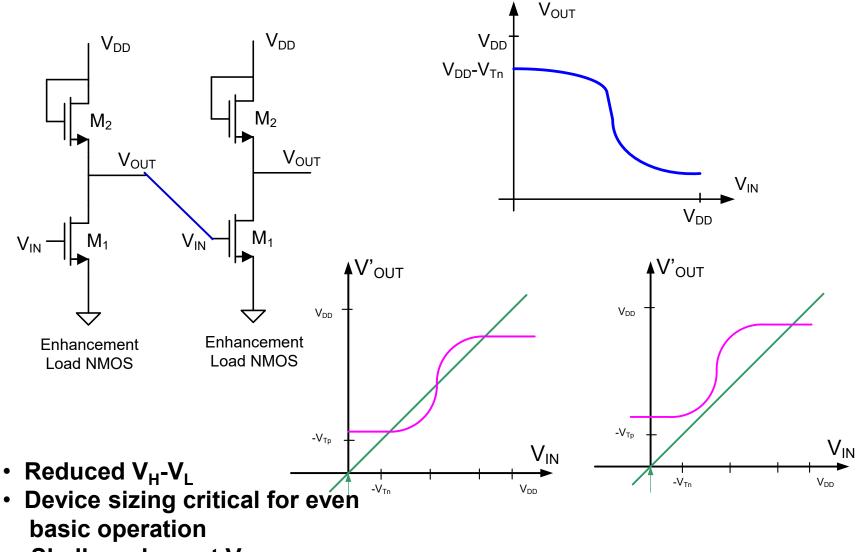
- Multiple-input gates require single transistor for each additional input
- Termed "ratio" logic

•

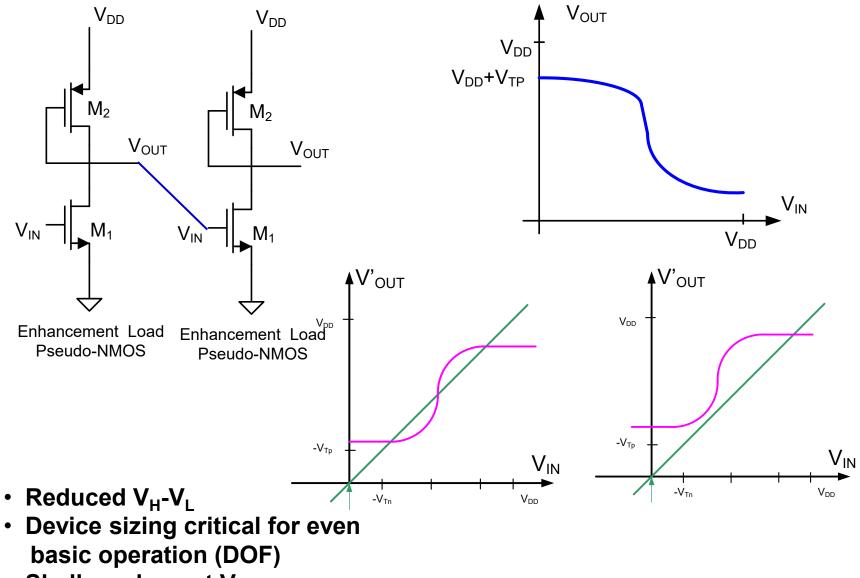
Available to use in standard CMOS process



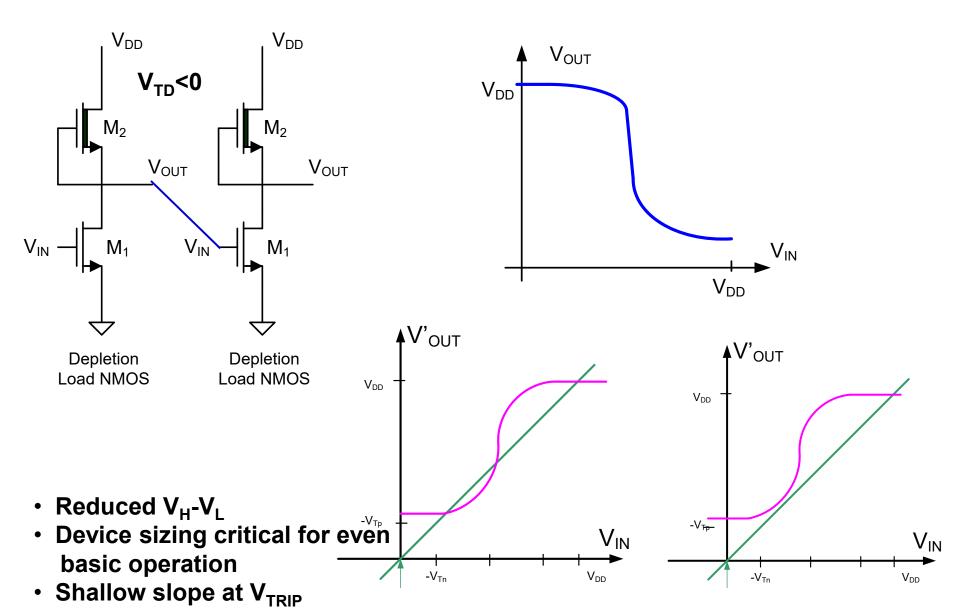




Shallow slope at V_{TRIP}



Shallow slope at V_{TRIP}



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Static Power Dissipation in Static CMOS Family

Von M_2 VIN PUN V_{OUT} VIN PDN

When V_{IN} is Low and V_{OUT} is High, M_1 is off and $I_{D1}=0$ When V_{IN} is High and V_{OUT} is Low, M_2 is off and $I_{D2}=0$

Thus, P_{STATIC}=0

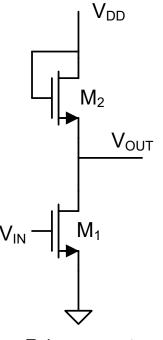
This is a key property of the static CMOS Logic Family → the major reason Static CMOS Logic is so dominant

It can be shown that this zero static power dissipation property can be preserved if the PUN is comprised of p-channel devices, the PDN is comprised of n-channel devices and they are never both driven into the conducting states at the same time

Compound Gate in CMOS Process

Static Power Dissipation in Ratio Logic Families

Example:



Assume V_{DD} =5V V_{Tn} =1V, μC_{OX} =10⁻⁴A/V², W_1/L_1 =1 and M_2 sized so that V_L is close to V_{Tn}

Observe:

I,

 $V_H = V_{DD} - V_{Tn}$

If $V_{IN}=V_H$, $V_{OUT}=V_L$ so

$$I_{D1} = \frac{\mu C_{OX} W_1}{L_1} \left(V_{GS1} - V_{Tn} - \frac{V_{DS1}}{2} \right) V_{DS1}$$

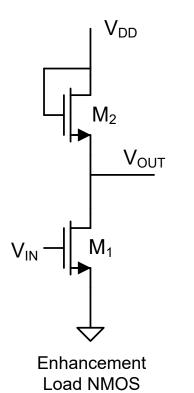
$$= 10^{-4} \left(5 - 1 - 1 - \frac{1}{2} \right) \cdot 1 = 0.25 \text{mA}$$

P_L=(5V)(0.25mA)=1.25mW

Enhancement Load NMOS

Static Power Dissipation in Ratio Logic Families

Example:



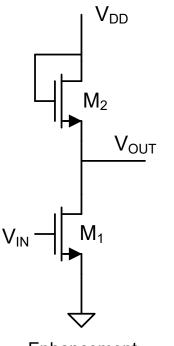
Assume V_{DD} =5V V_T =1V, μC_{OX} =10⁻⁴A/V², W_1/L_1 =1 and M_2 sized so that V_L is close to V_{Tn}

P_L=(5V)(0.25mA)=1.25mW

If a circuit has 100,000 gates and half of them are in the $V_{OUT}=V_L$ state, the static power dissipation will be

Static Power Dissipation in Ratio Logic Families

Example:



Enhancement Load NMOS

Assume V_{DD} =5V V_T =1V, μC_{OX} =10⁻⁴A/V², W_1/L_1 =1 and M_2 sized so that V_L is close to V_{Tn}

P_L=(5V)(0.25mA)=1.25mW

If a circuit has 100,000 gates and half of them are in the $V_{OUT}=V_L$ state, the static power dissipation will be

$$P_{STATIC} = \frac{1}{2} 10^5 \bullet 1.25 \, mW = 62.5W$$

This power dissipation is way too high and would be even larger in circuits with 100 million or more gates – the level of integration common in SoC circuits today

Digital Circuit Design

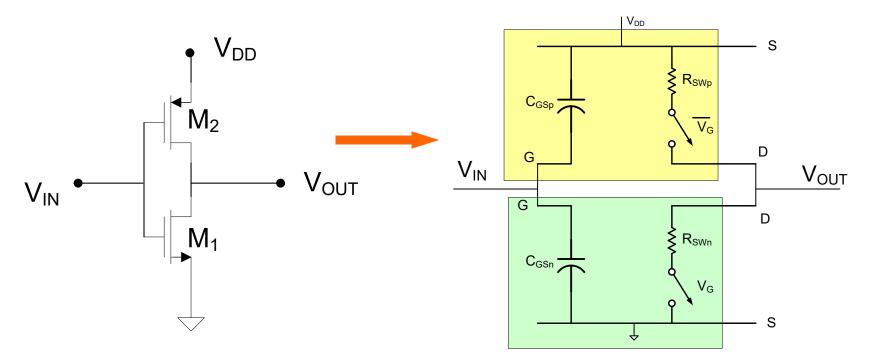
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Propagation Delay in Static CMOS Family

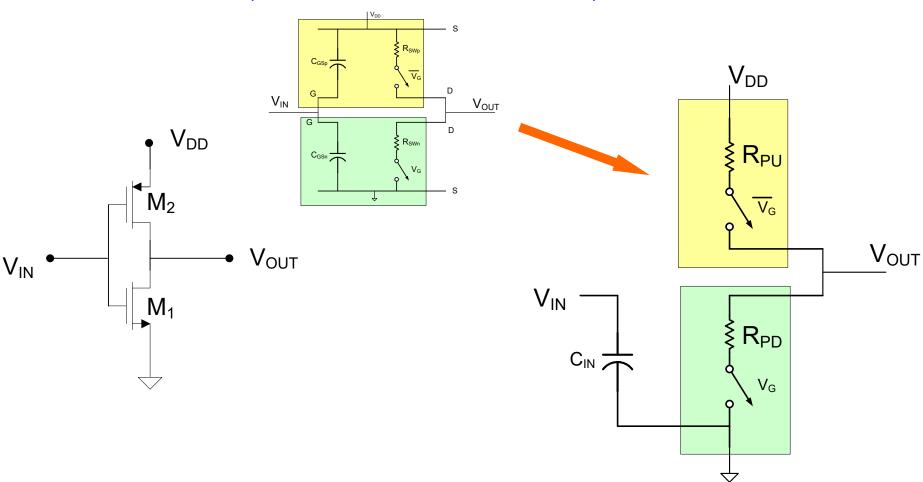
(Review from earlier discussions)



Switch-level model of Static CMOS inverter (neglecting diffusion parasitics)

Propagation Delay in Static CMOS Family

(Review from earlier discussions)



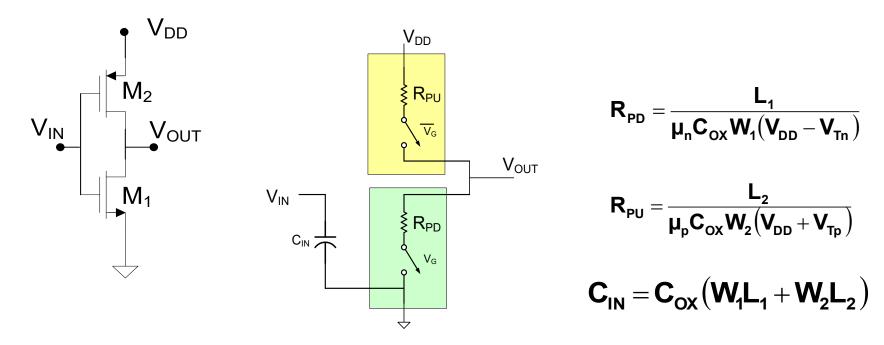
Switch-level model of Static CMOS inverter (neglecting diffusion parasitics)

Propagation Delay in Static CMOS Family (Review from earlier discussions) VDD V_{DD} R_{PU} VOUT V_{IN} ξ R_{PD} Since conducting transistor operating in triode through most of transition: $\mathbf{I}_{\mathsf{D}} \cong \frac{\mu \mathbf{C}_{\mathsf{OX}} \mathbf{W}}{\mathbf{I}} \Big(\mathbf{V}_{\mathsf{GS}} - \mathbf{V}_{\mathsf{T}} - \frac{\mathbf{V}_{\mathsf{DS}}}{2} \Big) \mathbf{V}_{\mathsf{DS}} \cong \frac{\mu \mathbf{C}_{\mathsf{OX}} \mathbf{W}}{\mathbf{I}} \big(\mathbf{V}_{\mathsf{GS}} - \mathbf{V}_{\mathsf{T}} \big) \mathbf{V}_{\mathsf{DS}}$ \Rightarrow

 $R_{PU} = \frac{V_{DS}}{I_{D}} = \frac{L_{2}}{\mu_{p}C_{OX}W_{2}(V_{DD} + V_{Tp})}$ $C_{IN} = C_{OX}(W_{1}L_{1} + W_{2}L_{2})$

 $R_{PD} = \frac{V_{DS}}{I_{D}} = \frac{L_{1}}{\mu_{D}C_{OV}W_{1}(V_{DD} - V_{TD})}$

(Review from earlier discussions)



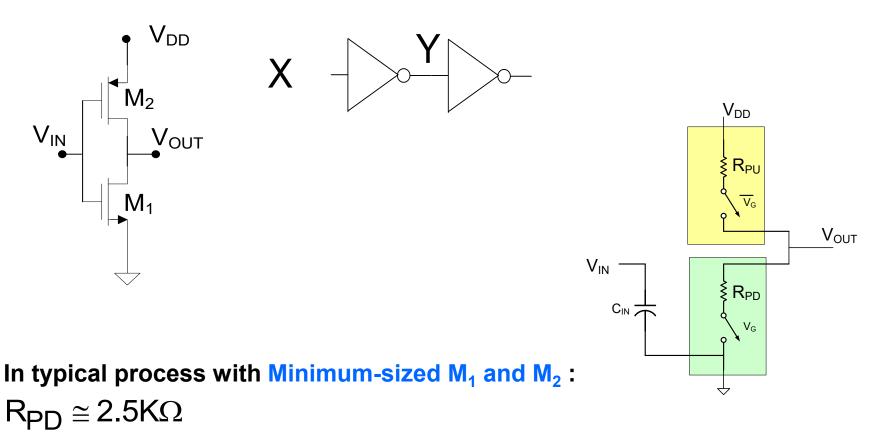
Example: Minimum-sized M₁ and M₂

If $u_n C_{OX}$ =100µAV⁻², C_{OX} =4 fFµ⁻², V_{Tn} = V_{DD} /5, V_{TP} =- V_{DD} /5, μ_n/μ_p =3, L_1 = W_1 = L_{MIN} , L_2 = W_2 = L_{MIN} , L_{MIN} =0.5µ and V_{DD} =5V (Note: This C_{ox} is somewhat larger than that in the 0.5u ON process)

$$R_{PD} = \frac{1}{10^{-4} \cdot 0.8V_{DD}} = 2.5K\Omega$$

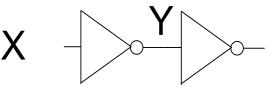
$$C_{IN} = 4 \cdot 10^{-15} \cdot 2L_{MIN}^{2} = 2fF$$

$$R_{PU} = \frac{1}{10^{-4} \cdot \frac{1}{3} \cdot 0.8V_{DD}} = 7.5K\Omega$$

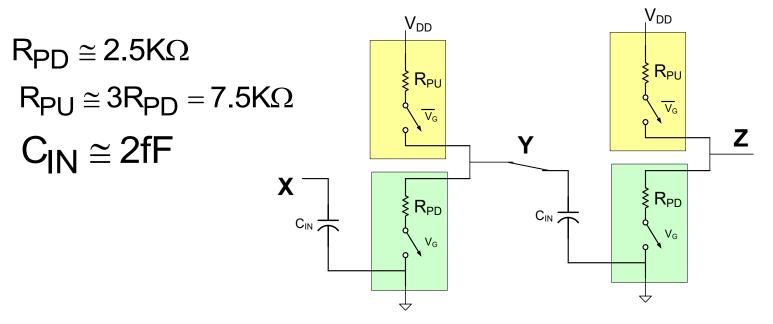


$$R_{PU} \cong 3R_{PD} = 7.5K\Omega$$

(Review from earlier discussions)



In typical process with Minimum-sized M_1 and M_2 :

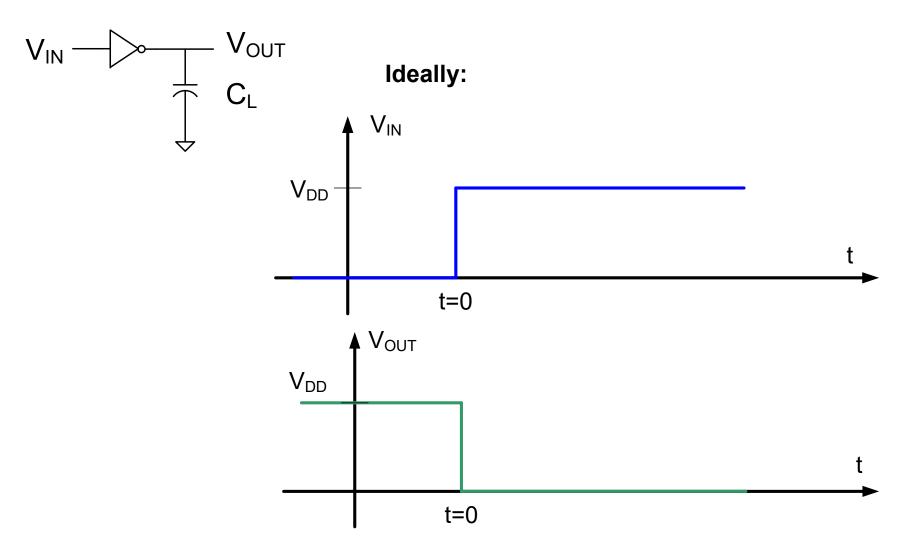


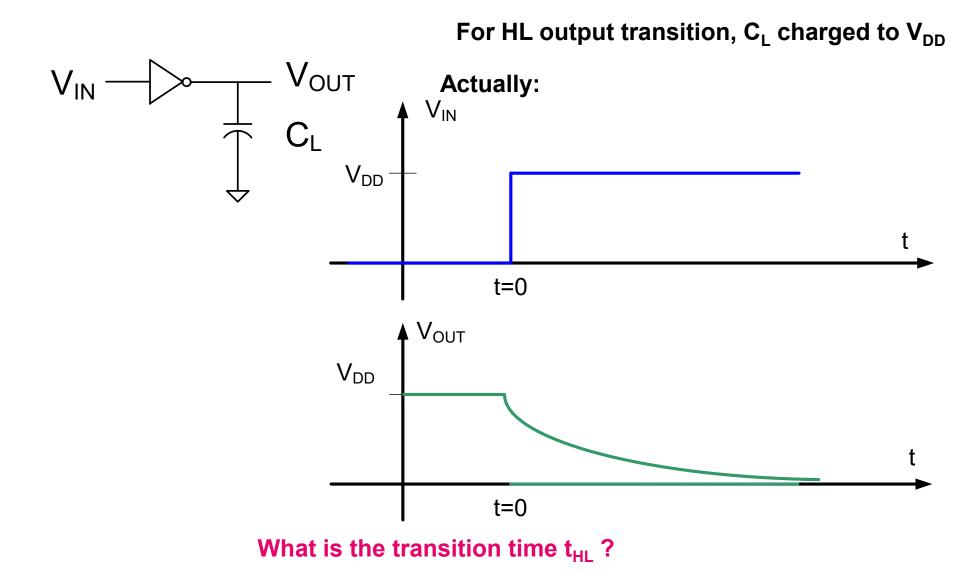
How long does it take for a signal to propagate from x to y?

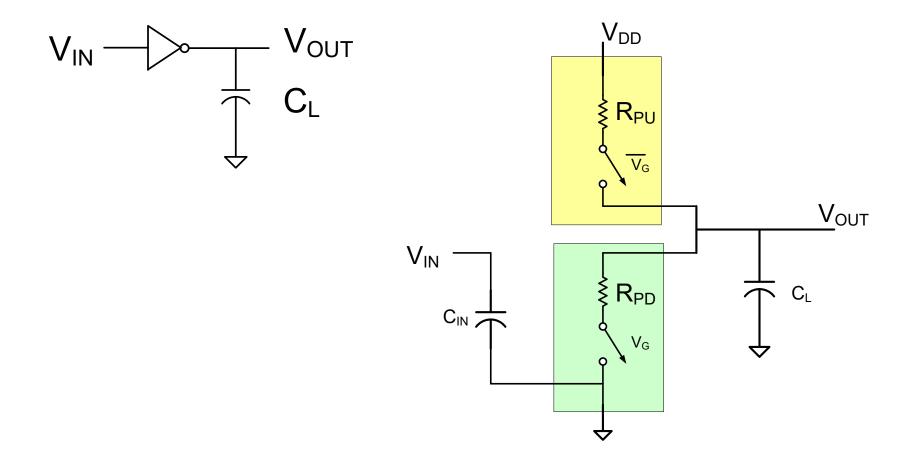
(Review from earlier discussions)

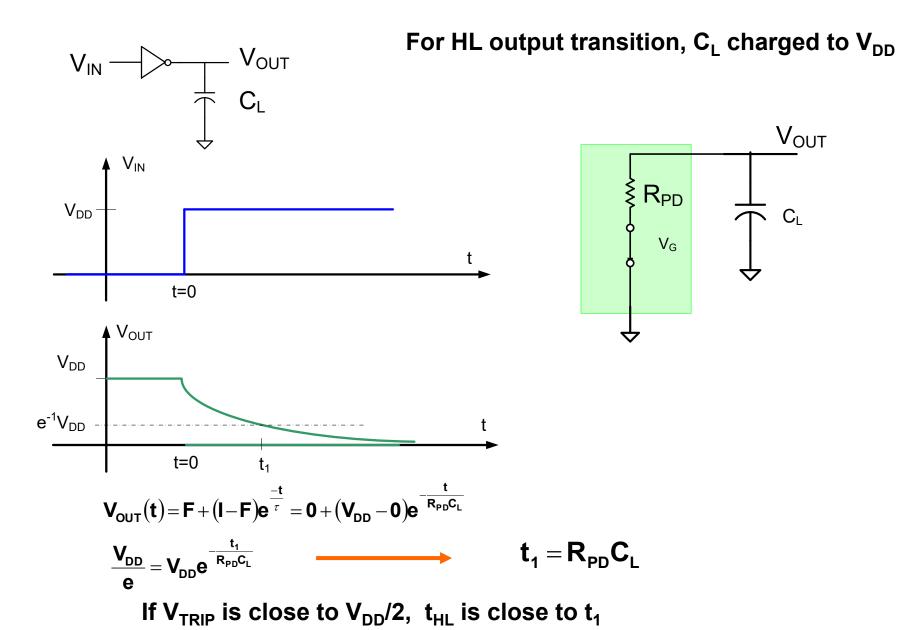
Consider:

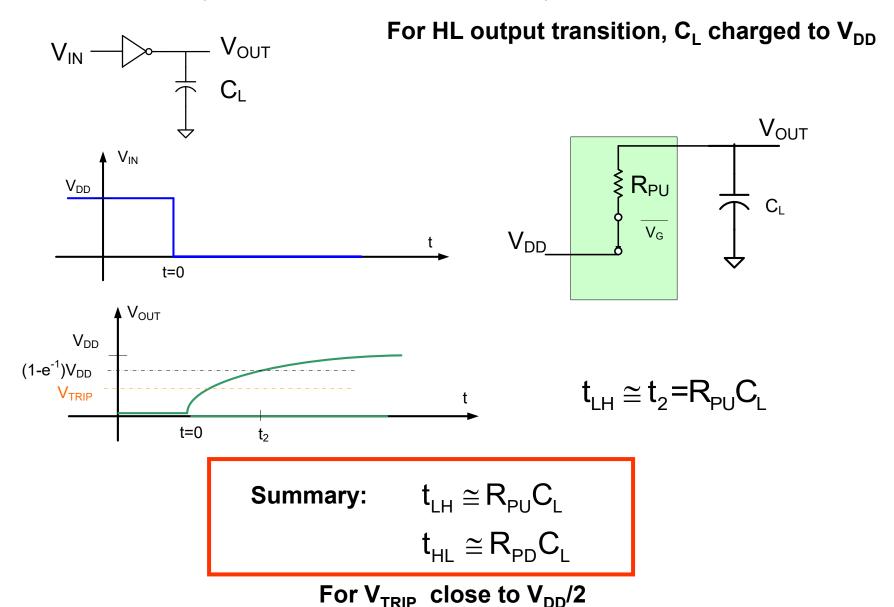
For HL output transition, C_L charged to V_{DD}



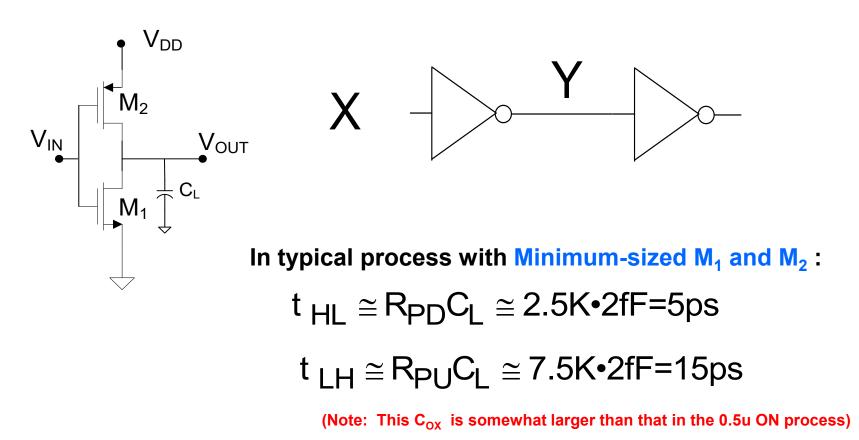








(Review from earlier discussions)



Note: LH transition is much slower than HL transition

Defn: The Propagation Delay of a gate is defined to be the sum of t_{HL} and t_{LH} , that is, t_{PROP} = t_{HL} + t_{LH}

$$\mathsf{t}_{\mathsf{PROP}} = \mathsf{t}_{\mathsf{HL}} + \mathsf{t}_{\mathsf{LH}} \cong \mathsf{C}_{\mathsf{L}} (\mathsf{R}_{\mathsf{PU}} + \mathsf{R}_{\mathsf{PD}})$$

Propagation delay represents a fundamental limit on the speed a gate can be clocked at

For basic two-inverter cascade <u>with minimum-sized devices</u> in static 0.5um CMOS logic driving an identical device

X
$$-$$
 Y $+$ $t_{PROP} = t_{HL} + t_{LH} \cong 20 p \text{ sec}$

Propagation Delay in Static CMOS Family
for Arbitrarily Sized Devices

$$t_{PROP} = t_{HL} + t_{LH} \cong C_L (R_{PU} + R_{PD})$$

 $R_{PD} = \frac{L_1}{\mu_P C_{0X} W_1 (V_{DD} - V_{TD})}$
 $R_{PU} = \frac{L_2}{\mu_P C_{0X} W_2 (V_{DD} + V_{TD})}$
 $C_{IN} = C_{0X} (W_1 L_1 + W_2 L_2)$
If $V_{Tn} = -V_{Tp} = V_T$ and if $C_L = C_{IN}$
 $t_{PROP} = C_{0X} (W_1 L_1 + W_2 L_2) \left(\frac{L_1}{\mu_R C_{0X} W_1 (V_{DD} - V_T)} + \frac{L_2}{\mu_P C_{0X} W_2 (V_{DD} - V_T)} \right)$
If $L_2 = L_1 = L_{min}, \mu_n = 3\mu_p$,
 $t_{PROP} = \frac{L_{min}^2}{\mu_n (V_{DD} - V_T)} (W_1 + W_2) \left(\frac{1}{W_1} + \frac{3}{W_2} \right) = \frac{L_{min}^2}{\mu_n (V_{DD} - V_T)} (4 + \frac{W_2}{W_1} + 3\frac{W_1}{W_2})$

Note speed is a function of device sizing !

Can t_{PROP} be minimized?

Propagation Delay in Static CMOS Family for Arbitrarily Sized Devices

For
$$L_2 = L_1 = L_{\min}, \ \mu_n = 3\mu_p,$$

 $t_{PROP} = \frac{L_{\min}^2}{\mu_n (V_{DD} - V_T)} (4 + \frac{W_2}{W_1} + 3\frac{W_1}{W_2})$

Can t_{PROP} be minimized?

Assume $W_1 = W_{MIN}$

$$\begin{aligned} \frac{\partial t_{\text{PROP}}}{\partial W_2} = & \left[\frac{L_{\text{min}}^2}{\mu_n \left(V_{\text{DD}} - V_{\text{TH}} \right)} \right] \left[\frac{1}{W_{\text{MIN}}} - 3 \frac{W_{\text{MIN}}}{W_2^2} \right] = 0 \\ & \frac{1}{W_{\text{MIN}}} - 3 \frac{W_{\text{MIN}}}{W_2^2} = 0 \end{aligned}$$

$$W_{2} = \sqrt{3}W_{MIN}$$

$$t_{PROP} = \frac{L_{min}^{2}}{\mu_{n}(V_{DD} - V_{T})} (4 + 2\sqrt{3}) \cong \frac{L_{min}^{2}}{\mu_{n}(V_{DD} - V_{T})} (7.5)$$

$\begin{array}{l} Propagation \ Delay \ in \ Static \ CMOS \ Family \\ \underline{for \ Arbitrarily \ Sized \ Devices} \\ t \ _{PROP} = t \ _{HL} + t \ _{LH} \cong C_L \left(R_{PU} + R_{PD} \right) \\ \end{array}$ $\begin{array}{l} \text{If } V_{T_n} = - V_{T_p} = V_T \ \text{and} \ C_L = C_{IN} \end{array}$

For min size:

$$t_{PROP} = C_{OX}(W_{1}L_{1} + W_{2}L_{2}) \left(\frac{L_{1}}{\mu_{n}C_{OX}W_{1}(V_{DD} - V_{T})} + \frac{L_{2}}{\mu_{p}C_{OX}W_{2}(V_{DD} - V_{T})} \right)$$

If $L_{2} = L_{1} = L_{min}, W_{1} = W_{2} = W_{min}, \mu_{n} = 3\mu_{p},$
 $t_{PROP} = \frac{L_{min}^{2}}{\mu_{n}(V_{DD} - V_{T})} (W_{1} + W_{2}) \left(\frac{1}{W_{1}} + \frac{3}{W_{2}} \right) = \frac{L_{min}^{2}}{\mu_{n}(V_{DD} - V_{T})} (2W_{min}) \left(\frac{1}{W_{min}} + \frac{3}{W_{min}} \right)$

For min size:

$$W_{2} = W_{1} = W_{min}$$
$$t_{PROP} = \frac{8L_{min}^{2}}{\mu_{n}(V_{DD} - V_{T})}$$

Propagation Delay in Static CMOS Family for Arbitrarily Sized Devices

$$t_{PROP} = t_{HL} + t_{LH} \cong C_L (R_{PU} + R_{PD})$$

If V_{Tn} =- V_{Tp} = V_T and C_L = C_{IN}

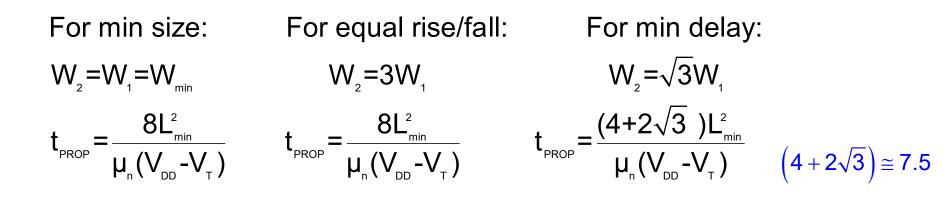
For equal rise/fall:

$$W_{2} = 3W_{1}$$

 $t_{PROP} = \frac{8L_{min}^{2}}{\mu_{n}(V_{DD} - V_{T})}$

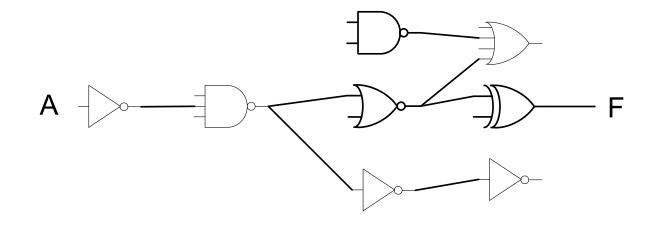
Propagation Delay in Static CMOS Family t _{PROP} = t _{HL}+t _{LH} \cong C_L (R_{PU} + R_{PD}) Summary:

If V_{Tn} =- V_{Tp} = V_T and C_L = C_{IN} and $L_2 = L_1 = L_{min}$, $\mu_n = 3\mu_p$,



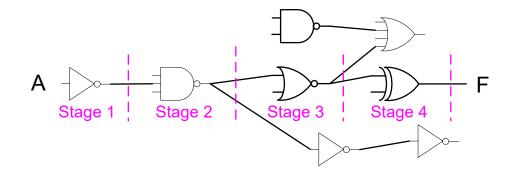
Propagation Delay About the Same for 3 Sizing Strategies

And for these sizing strategies all are near that of minimum delay !



The propagation delay through k levels of logic is approximately the sum of the individual propagation delays in the same path

Example:



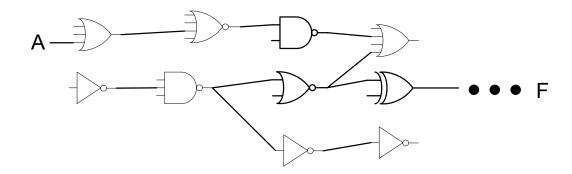
 $\mathbf{t}_{\mathsf{HL}} = \mathbf{t}_{\mathsf{HL4}} + \mathbf{t}_{\mathsf{LH3}} + \mathbf{t}_{\mathsf{HL2}} + \mathbf{t}_{\mathsf{LH1}}$

 $\mathbf{t}_{\text{LH}} = \mathbf{t}_{\text{LH4}} + \mathbf{t}_{\text{HL3}} + \mathbf{t}_{\text{LH2}} + \mathbf{t}_{\text{HL1}}$

 $t_{PROP} = t_{LH} + t_{HL} = (t_{LH4} + t_{HL3} + t_{LH2} + t_{HL1}) + (t_{HL4} + t_{LH3} + t_{HL2} + t_{LH1})$

 $t_{PROP} = t_{LH} + t_{HL} = (t_{LH4} + t_{HL4}) + (t_{LH3} + t_{HL3}) + (t_{LH2} + t_{HL2}) + (t_{LH1} + t_{HL1})$

t_{PROP}=t_{PROP4}+t_{PROP3}+t_{PROP2}+t_{PROP1}



Propagation through k levels of logic

$$t_{\text{HL}} \cong t_{\text{HLk}} + t_{\text{LH}(k-1)} + t_{\text{HL}(k-2)} + \cdots + t_{\text{XY1}}$$
$$t_{\text{LH}} \cong t_{\text{LHk}} + t_{\text{HL}(k-1)} + t_{\text{LH}(k-2)} + \cdots + t_{\text{YX1}}$$

where X=H and Y=L if k odd and X=L and Y=h if k even

$$t_{PROP} = \sum_{i=1}^{k} t_{PROPk}$$

Will return to propagation delay after we discuss device sizing in more detail



Stay Safe and Stay Healthy !

End of Lecture 39